# MICROWAVE POWER GaAs FET

#### **PRELIMINARY**

#### **Features**

- · Low intermodulation distortion
  - $IM_3 = -45 \text{ dBc at Po} = 35.0 \text{ dBm}$
- · High power
- P<sub>1dB</sub> = 45.5 dBm at 5.9 to 6.4 GHz
  High efficiency
- $\eta_{add}$  = 37% at 5.9 to 6.4 GHz
- High gain
  - $G_{1dB} = 8.0 \text{ dB}$  at 5.9 to 6.4 GHz
- · Broadband internally matched
- · Hermetically sealed package

## RF Performance Specifications (T<sub>a</sub> = 25°C)

Characteristic	Symbol	Condition	Unit	Min.	Тур.	Max.
Output Power at 1dB Compression Point	P <sub>1dB</sub>	V <sub>DS</sub> = 10V f = 5.9 ~ 6.4 GHz	dBm	45.0	45.5	-
Power Gain at 1dB Compression Point	G <sub>1dB</sub>		dB	7.0	8.0	-
Drain Current	$I_{DS}$		Α	-	8.0	9.0
Power Added Efficiency	$\eta_{add}$		%	-	37	-
3rd Order Intermodulation Distortion	IM <sub>3</sub>	Note 1	dBc	-42	-45	-
Channel-Temperature Rise	$\Delta T_{ch}$	V <sub>DS</sub> x I <sub>DS</sub> x R <sub>th (c-c)</sub>	°C	-	-	100

Note 1: 2-tone Test Pout, Po = 35 dBm Single Carrier Level.

# Electrical Characteristics (T<sub>a</sub> = 25°C)

Characteristic	Symbol	Condition	Unit	Min.	Тур.	Max.
Transconductance	gm	$V_{DS} = 3V$ $I_{DS} = 10.5A$	mS	_	6500	-
Pinch-off Voltage	V <sub>GSoff</sub>	$V_{DS} = 3V$ $I_{DS} = 140 \text{ mA}$	V	-1.0	-2.5	-4.0
Saturated Drain Current	I <sub>DSS</sub>	$V_{DS} = 3V$ $V_{GS} = 0V$	Α	-	20	26
Gate-Source Breakdown Voltage	$V_{GSO}$	I <sub>GS</sub> = -420 μA	V	-5	-	-
Thermal Resistance	R <sub>th (c-c)</sub>	Channel to Case	°C/W	-	1.0	1.3

The information contained here is subject to change without notice.

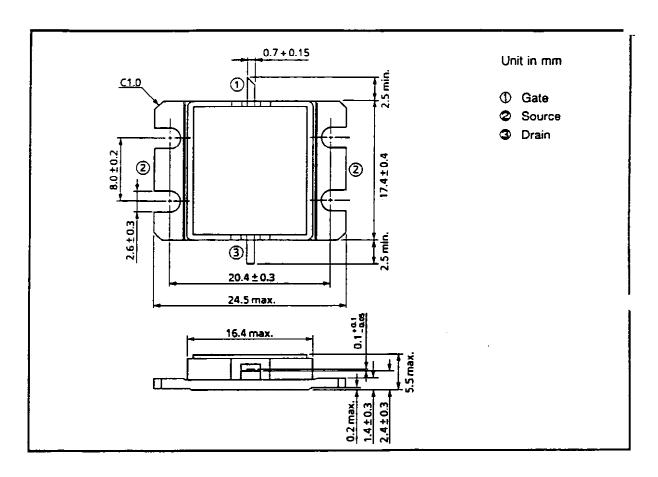
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# Absolute Maximum Ratings ( $T_a = 25^{\circ}C$ )

Characteristic	Symbol	Unit	Rating
Drain-Source Voltage	$V_{DS}$	V	15
Gate-Source Voltage	$V_{GS}$	V	-5
Drain Current	I <sub>DS</sub>	Α	26
Total Power Dissipation (T <sub>C</sub> = 25°C)	P <sub>T</sub>	W	115
Channel Temperature	T <sub>ch</sub>	°C	175
Storage Temperature	T <sub>stg</sub>	°C	-65 ~ 175

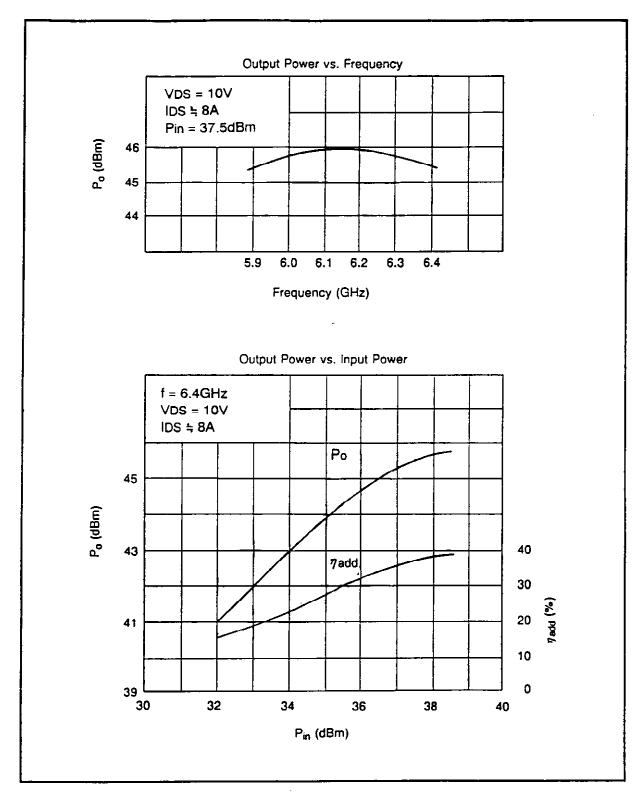
## Package Outline (2-16G1B)



# **Handling Precautions for Packaged Type**

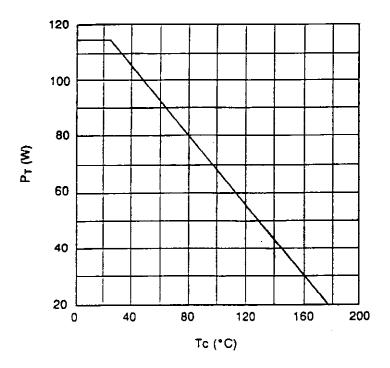
Soldering iron should be grounded and the operating time should not exceed 10 seconds at 260°C.

## **RF Performances**

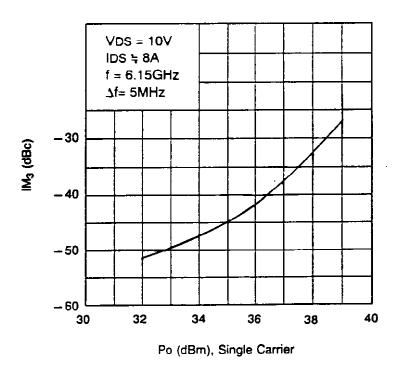


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# **Power Dissipation vs. Case Temperature**



# IM<sub>3</sub> vs. Output Power Characteristics



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